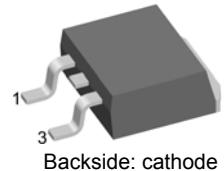
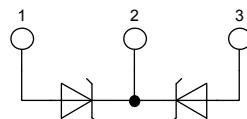


# Schottky Diode

High Performance Schottky Diode  
Low Loss and Soft Recovery  
Common Cathode

Part number

DSSK18-0025BS



## Features / Advantages:

- Very low  $V_f$
- Extremely low switching losses
- low  $I_{rm}$  values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching

## Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

## Package:

- Housing: TO-263 (D2Pak)
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

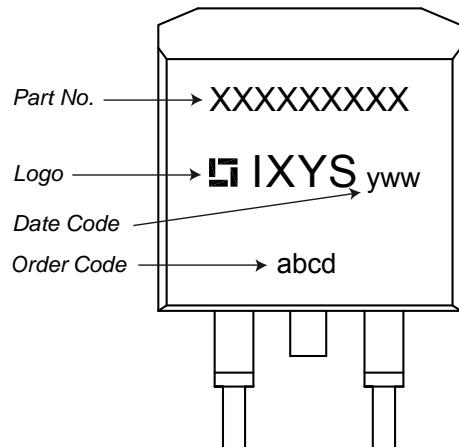
Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	Unit
$V_{RRM}$	max. repetitive reverse voltage	$T_{VJ} = 25^\circ\text{C}$			25	V
$I_R$	reverse current	$V_R = 25\text{V}$ $T_{VJ} = 25^\circ\text{C}$ $V_R = 25\text{V}$ $T_{VJ} = 100^\circ\text{C}$			10	mA
$V_F$	forward voltage	$I_F = 10\text{A}$ $T_{VJ} = 25^\circ\text{C}$ $I_F = 20\text{A}$ $I_F = 10\text{A}$ $T_{VJ} = 125^\circ\text{C}$ $I_F = 20\text{A}$			0.45	V
$I_{FAV}$	average forward current	rectangular, $d = 0.5$ $T_C = 140^\circ\text{C}$			10	A
$V_{F0}$	threshold voltage	$T_{VJ} = 150^\circ\text{C}$			0.20	V
$r_F$	slope resistance } for power loss calculation only				14.6	mΩ
$R_{thJC}$	thermal resistance junction to case				1.70	K/W
$T_{VJ}$	virtual junction temperature		-55		150	°C
$P_{tot}$	total power dissipation	$T_C = 25^\circ\text{C}$			75	W
$I_{FSM}$	max. forward surge current	$t = 10\text{ ms}$ (50 Hz), sine $T_{VJ} = 45^\circ\text{C}$			140	A
$C_J$	junction capacitance	$V_R = \text{tbd V}; f = 1\text{ MHz}$ $T_{VJ} = 25^\circ\text{C}$		tbd		pF

Symbol	Definition	Conditions	Ratings		
			min.	typ.	max.
$I_{RMS}$	RMS current	per pin <sup>1)</sup>			35
$R_{thCH}$	thermal resistance case to heatsink			0.25	K/W
$T_{stg}$	storage temperature		-55		150
<b>Weight</b>				2	g
$F_c$	mounting force with clip		20		60
					N

<sup>1)</sup>  $I_{RMS}$  is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

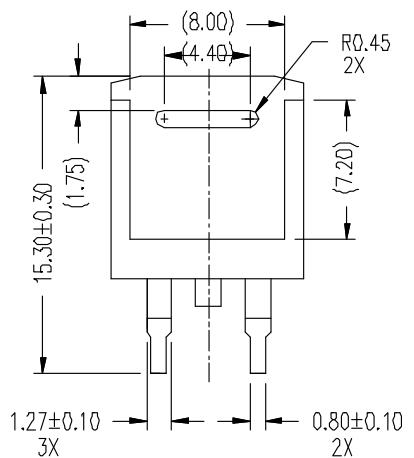
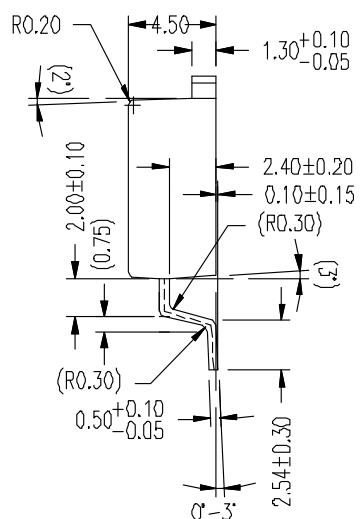
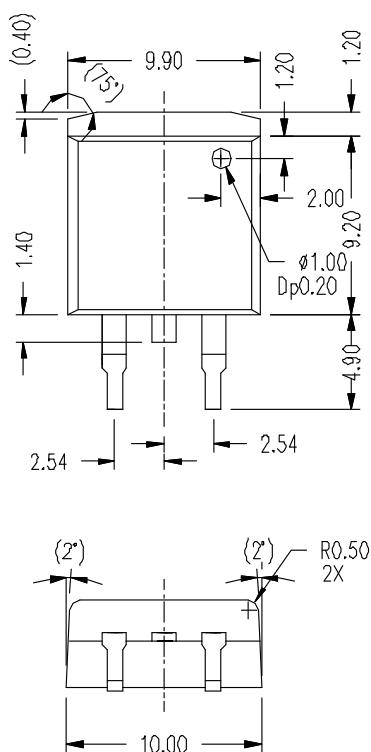
## Product Marking



Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	DSSK18-0025BS	DSSK18-0025BS	Tape and Reel	800	499099

Similar Part	Package	Voltage class
DSB30C30PB	TO-220	30

## Outlines TO-263 (D2Pak)



**NOTE:**

- NOTE:  
 1. These dimensions do not include mold protusion.  
 2. ( ) is reference dimension only.